

### Flangeless Termination 50 Ω



#### General Specifications

<b>Resistive Element</b>	Thick film
<b>Substrate</b>	Alumina Ceramic
<b>Terminal Finish</b>	Thick film Silver
<b>Lead(s)</b>	99.99% pure silver (.005" thk.)
<b>Operating Temperature</b>	-55 to +125°C (see chart)

Tolerance is  $\pm 0.010$ ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches. Lead length 0.15" minimum.

Specifications subject to change without notice.

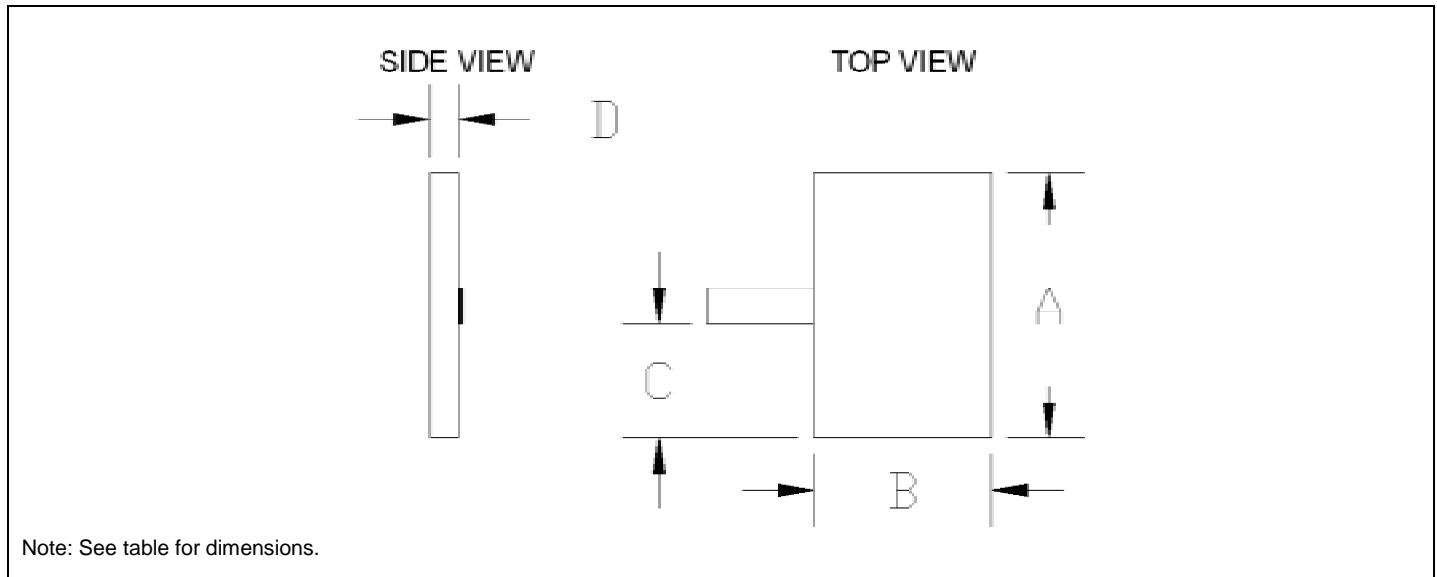
#### Features:

- DC – 4.2GHz
- 20-40 Watts
- Low Cost
- Alumina Ceramic
- Non-Nichrome Resistive Element
- 100% Tested

#### Dimensions

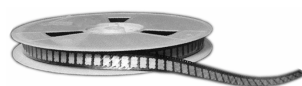
PART NUMBER	A	B	C	D
RFP-20A50T	0.100	0.200	0.025	0.025
RFP-30A50TPP	0.250	0.250	0.100	0.040
RFP-40A50TEN	0.250	0.375	0.100	0.040
RFP-40A50TB	0.375	0.250	0.162	0.040
RFP-40A50TD	0.375	0.375	0.128	0.040

#### Outline Drawing



Note: See table for dimensions.

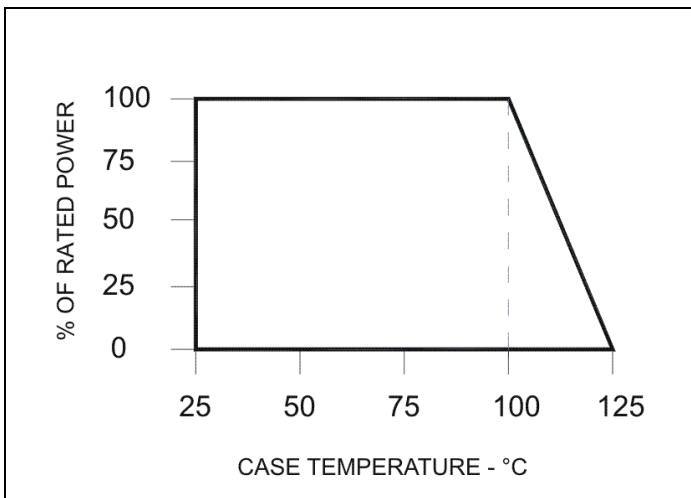
Rev. 11/03/04



### Typical Performance

PART NUMBER	VALUE ( $\Omega$ )	POWER (WATTS)	MAX VSWR	FREQ. (GHz)
RFP-20A50T	50	20	1.25:1	4.2
RFP-30A50TPP	50	30	1.25:1	3.0
RFP-40A50TEN	50	40	1.25:1	3.0
RFP-40A50TD	50	40	1.20:1	3.0
RFP-40A50TB	50	40	1.20:1	2.5

### Power De-rating



### Suggested Mounting Procedures

#### Suggested Mounting Procedure

**SUGGESTED STRESS RELIEF METHODS**  
SCALE: \_\_\_\_\_

**NOT RECOMMENDED APPLICATION**  
SCALE: \_\_\_\_\_

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Position device on mounting surface and solder in place using an indalloy type or an SN63 type solder.
3. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).

